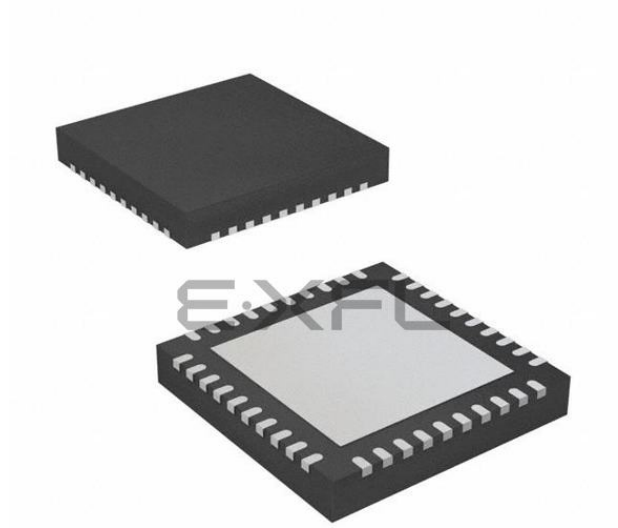

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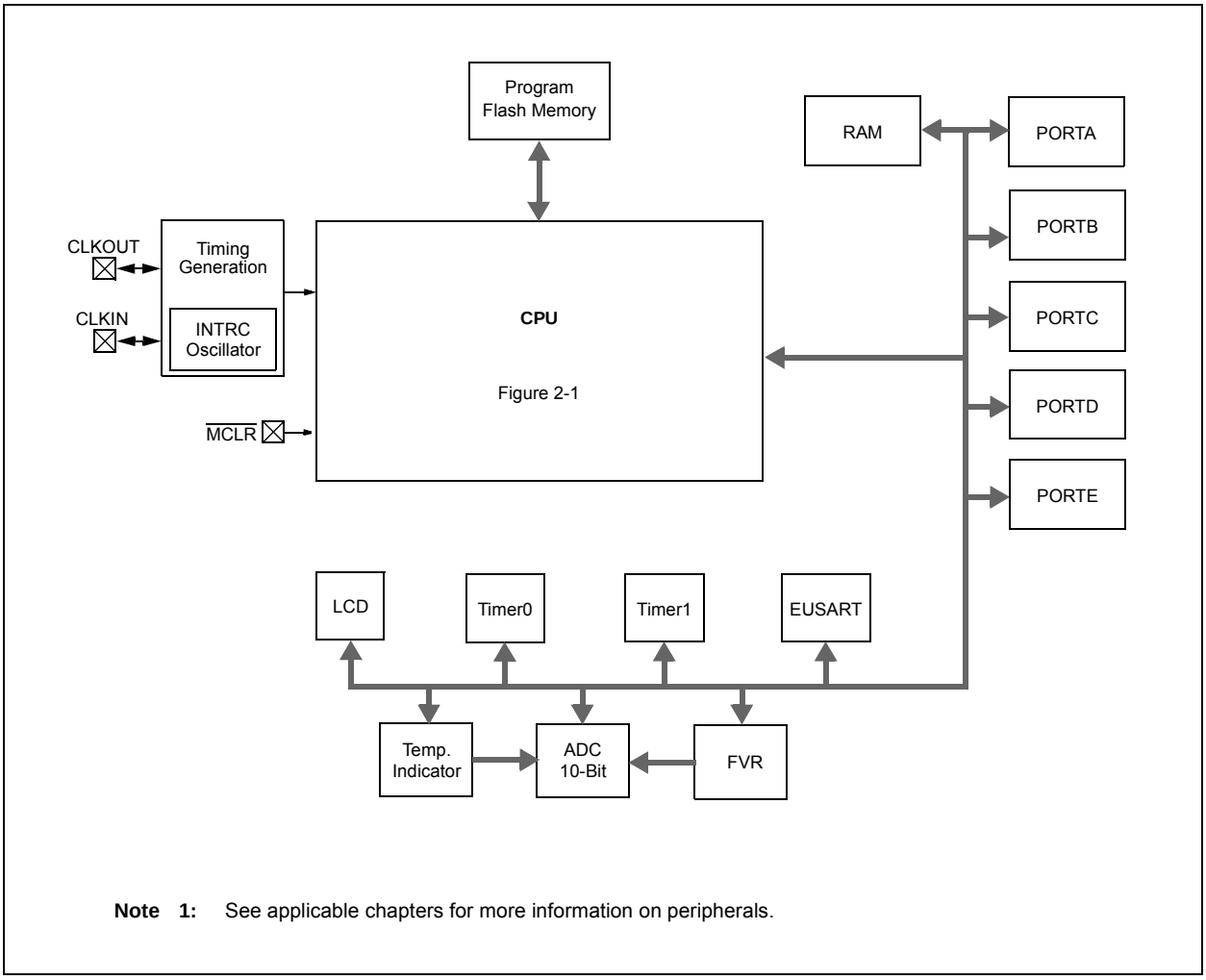
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1904t-i-mv

FIGURE 1-1: PIC16LF1904/6/7 BLOCK DIAGRAM



Note 1: See applicable chapters for more information on peripherals.

2.0 ENHANCED MID-RANGE CPU

This family of devices contain an enhanced mid-range 8-bit CPU core. The CPU has 49 instructions. Interrupt capability includes automatic context saving. The hardware stack is 16 levels deep and has Overflow and Underflow Reset capability. Direct, Indirect, and Relative addressing modes are available. Two File Select Registers (FSRs) provide the ability to read program and data memory.

- Automatic Interrupt Context Saving
- 16-level Stack with Overflow and Underflow
- File Select Registers
- Instruction Set

2.1 Automatic Interrupt Context Saving

During interrupts, certain registers are automatically saved in shadow registers and restored when returning from the interrupt. This saves stack space and user code. See **Section 7.5 "Automatic Context Saving"**, for more information.

2.2 16-Level Stack with Overflow and Underflow

These devices have an external stack memory 15 bits wide and 16 words deep. A Stack Overflow or Underflow will set the appropriate bit (STKOVF or STKUNF) in the PCON register, and if enabled, will cause a software Reset. See **Section 3.4 "Stack"** for more details.

2.3 File Select Registers

There are two 16-bit File Select Registers (FSR). FSRs can access all file registers and program memory, which allows one Data Pointer for all memory. When an FSR points to program memory, there is one additional instruction cycle in instructions using INDF to allow the data to be fetched. General purpose memory can now also be addressed linearly, providing the ability to access contiguous data larger than 80 bytes. There are also new instructions to support the FSRs. See **Section 3.5 "Indirect Addressing"** for more details.

2.4 Instruction Set

There are 49 instructions for the enhanced mid-range CPU to support the features of the CPU. See **Section 21.0 "Instruction Set Summary"** for more details.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 2											
10Ch	LATA	PORTA Data Latch								xxxx xxxx	uuuu uuuu
10Dh	LATB	PORTB Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATC	PORTC Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATD(3)	PORTD Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATE(3)	—	—	—	—	—	LATE2	LATE1	LATE0	---- -xxx	---- -uuu
111h to 115h	—	Unimplemented								—	—
116h	BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	10-- ---q	uu-- ---u
117h	FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR1	ADFVR0	0q00 --00	0q00 --00
118h to 11Fh	—	Unimplemented								—	—
Bank 3											
18Ch	ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	--1- 1111	--11 1111
18Dh	ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
18Eh	—	Unimplemented								—	—
18Fh	—	Unimplemented								—	—
190h	ANSELE(3)	—	—	—	—	—	ANSE2	ANSE1	ANSE0	---- -111	---- -111
191h	PMADRL	Program Memory Address Register Low Byte								0000 0000	0000 0000
192h	PMADRH	—(2)	Program Memory Address Register High Byte							1000 0000	1000 0000
193h	PMDATL	Program Memory Read Data Register Low Byte								xxxx xxxx	uuuu uuuu
194h	PMDATH	—	—	Program Memory Read Data Register High Byte						--xx xxxx	--uu uuuu
195h	PMCON1	—(2)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	1000 x000	1000 q000
196h	PMCON2	Program Memory Control Register 2								0000 0000	0000 0000
197h	—	Unimplemented								—	—
198h	—	Unimplemented								—	—
199h	RCREG	USART Receive Data Register								0000 0000	0000 0000
19Ah	TXREG	USART Transmit Data Register								0000 0000	0000 0000
19Bh	SPBRG	BRG<7:0>								0000 0000	0000 0000
19Ch	SPBRGH	BRG<15:8>								0000 0000	0000 0000
19Dh	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19Eh	TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	0000 0010
19Fh	BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	01-0 0-00	01-0 0-00
Bank 4											
20Ch	—	Unimplemented								—	—
20Dh	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	1111 1111	1111 1111
20Eh	—	Unimplemented								—	—
20Fh	—	Unimplemented								—	—
210h	WPUE	—	—	—	—	WPUE3	—	—	—	---- 1---	---- 1---
211h to 21Fh	—	Unimplemented								—	—
Bank 5											
28Ch — 29Fh	—	Unimplemented								—	—
Bank 6											
30Ch — 31Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16LF1904/7 only.

REGISTER 4-1: CONFIGURATION WORD 1

U-1	U-1	R/P-1	R/P-1	R/P-1	U-1
—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13-12 **Unimplemented:** Read as '1'

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **Unimplemented:** Read as '1'

bit 7 **$\overline{\text{CP}}$:** Code Protection bit
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUE3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

bit 2 **Unimplemented:** Read as '1'

bit 1-0 **FOSC<1:0>:** Oscillator Selection bits
00 = INTOSC oscillator: I/O function on CLKIN pin
01 = ECL: External Clock, Low-Power mode (0-0.5 MHz): device clock supplied to CLKIN pin
10 = ECM: External Clock, Medium-Power mode (0.5-4 MHz): device clock supplied to CLKIN pin
11 = ECH: External Clock, High-Power mode (4-20 MHz): device clock supplied to CLKIN pin

5.0 RESETS

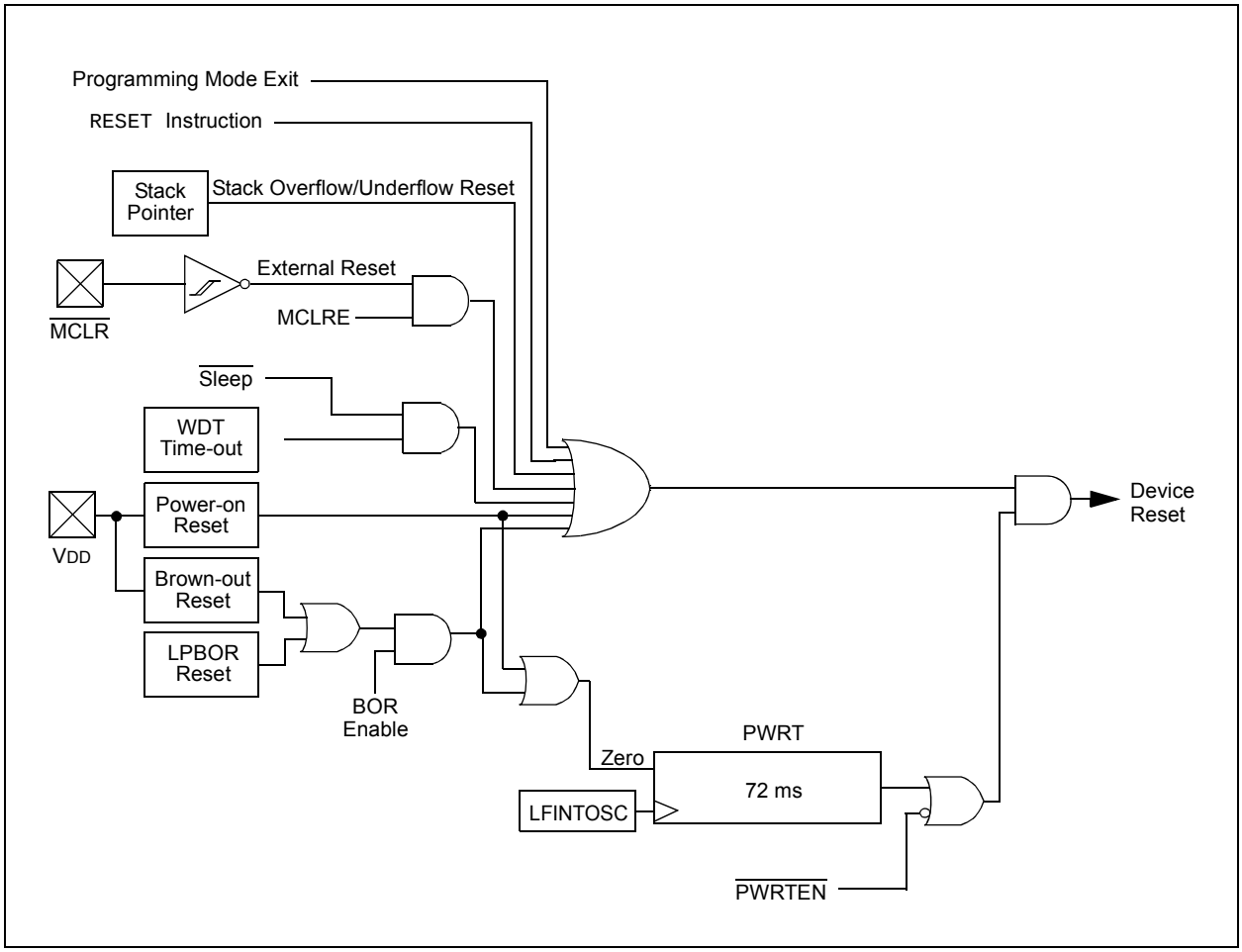
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- Low-Power Brown-out Reset (LPBOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional Power-up Timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



6.4 Oscillator Control Registers

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
—	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘0’

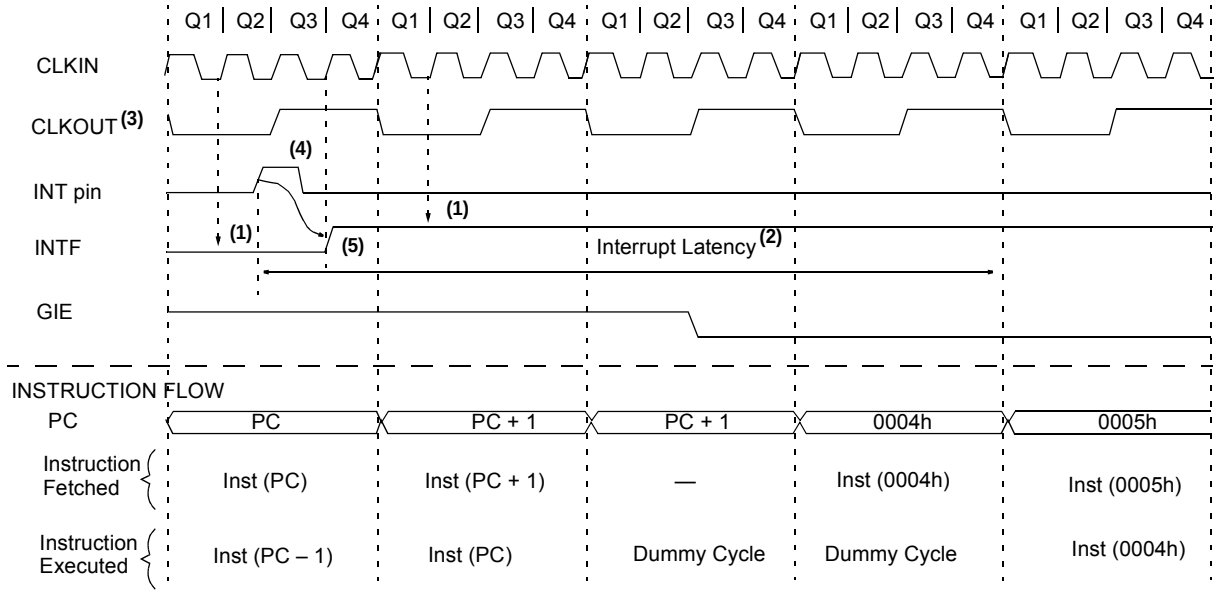
bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
000x = 31 kHz LF
001x = 31.25 kHz
0100 = 62.5 kHz
0101 = 125 kHz
0110 = 250 kHz
0111 = 500 kHz (default upon Reset)
1000 = 125 kHz(1)
1001 = 250 kHz(1)
1010 = 500 kHz(1)
1011 = 1 MHz
1100 = 2 MHz
1101 = 4 MHz
1110 = 8 MHz
1111 = 16 MHz

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Secondary oscillator
00 = Clock determined by FOSC<1:0> in Configuration Word 1.

Note 1: Duplicate frequency derived from HFINTOSC.

FIGURE 7-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all Oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 22.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

EXAMPLE 10-3: WRITING TO FLASH PROGRAM MEMORY

```
; This write routine assumes the following:
; 1. 64 bytes of data are loaded, starting at the address in DATA_ADDR
; 2. Each word of data to be written is made up of two adjacent bytes in DATA_ADDR,
;    stored in little endian format
; 3. A valid starting address (the least significant bits = 00000) is loaded in ADDRH:ADDRL
; 4. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)
;
        BCF         INTCON,GIE     ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRH         ; Bank 3
        MOVF        ADDRH,W        ; Load initial address
        MOVWF       PMADRH         ;
        MOVF        ADDRL,W        ;
        MOVWF       PMADRL         ;
        MOVLW       LOW DATA_ADDR  ; Load initial data address
        MOVWF       FSR0L          ;
        MOVLW       HIGH DATA_ADDR ; Load initial data address
        MOVWF       FSR0H          ;
        BCF         PMCON1,CFGS    ; Not configuration space
        BSF         PMCON1,WREN    ; Enable writes
        BSF         PMCON1,LWLO    ; Only Load Write Latches
LOOP
        MOVIW       FSR0++         ; Load first data byte into lower
        MOVWF       PMDATL         ;
        MOVIW       FSR0++         ; Load second data byte into upper
        MOVWF       PMDATH         ;

        MOVF        PMADRL,W       ; Check if lower bits of address are '00000'
        XORLW       0x1F           ; Check if we're on the last of 32 addresses
        ANDLW       0x1F           ;
        BTFSC       STATUS,Z       ; Exit if last of 32 words,
        GOTO        START_WRITE    ;

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       PMCON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       PMCON2         ; Write AAh
        BSF         PMCON1,WR      ; Set WR bit to begin write
        NOP                        ; NOP instructions are forced as processor
                                   ; loads program memory write latches
        NOP                        ;

        INCF        PMADRL,F       ; Still loading latches Increment address
        GOTO        LOOP           ; Write next latches

START_WRITE
        BCF         PMCON1,LWLO    ; No more loading latches - Actually start Flash program
                                   ; memory write

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       PMCON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       PMCON2         ; Write AAh
        BSF         PMCON1,WR      ; Set WR bit to begin write
        NOP                        ; NOP instructions are forced as processor writes
                                   ; all the program memory write latches simultaneously
        NOP                        ; to program memory.
                                   ; After NOPs, the processor
                                   ; stalls until the self-write process in complete
                                   ; after write processor continues with 3rd instruction
        BCF         PMCON1,WREN    ; Disable writes
        BSF         INTCON,GIE     ; Enable interrupts
```

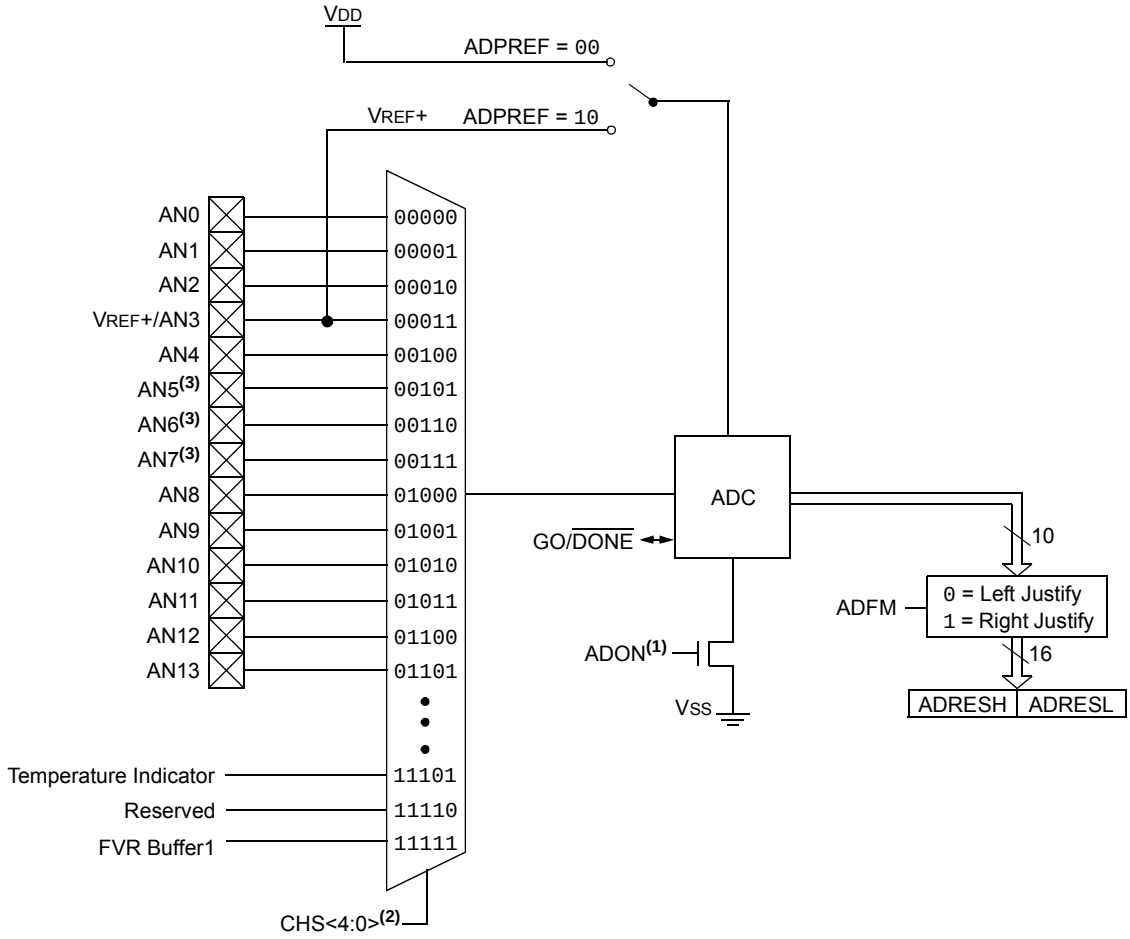
15.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 15-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 15-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

2: See ADCON0 register (Example 15-1) for detailed analog channel selection per device.

3: ADC channel is reserved on the PIC16LF1906 28-pin device.

REGISTER 15-2: ADCON1: A/D CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
ADFM	ADCS<2:0>			—	—	ADPREF<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ADFM:** A/D Result Format Select bit
- 1 = Right justified. Six Most Significant bits of ADRESH are set to '0' when the conversion result is loaded.
- 0 = Left justified. Six Least Significant bits of ADRESL are set to '0' when the conversion result is loaded.

bit 6-4 **ADCS<2:0>:** A/D Conversion Clock Select bits
- 000 = FOSC/2
- 001 = FOSC/8
- 010 = FOSC/32
- 011 = FRC (clock supplied from a dedicated RC oscillator)
- 100 = FOSC/4
- 101 = FOSC/16
- 110 = FOSC/64
- 111 = FRC (clock supplied from a dedicated RC oscillator)

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **ADPREF<1:0>:** A/D Positive Voltage Reference Configuration bits
- 00 = VREF+ is connected to VDD
- 01 = Reserved
- 10 = VREF+ is connected to external VREF+ pin(1)
- 11 = Reserved

Note 1: When selecting the FVR or the VREF+ pin as the source of the positive reference, be aware that a minimum voltage specification exists. See **Section 22.0 "Electrical Specifications"** for details.

17.1 Timer1 Operation

The Timer1 module is a 16-bit incrementing counter which is accessed through the TMR1H:TMR1L register pair. Writes to TMR1H or TMR1L directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1 is enabled by configuring the TMR1ON and TMR1GE bits in the T1CON and T1GCON registers, respectively. Table 17-1 displays the Timer1 enable selections.

TABLE 17-1: TIMER1 ENABLE SELECTIONS

TMR1ON	TMR1GE	Timer1 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

17.2 Clock Source Selection

The TMR1CS<1:0> and T1OSCEN bits of the T1CON register are used to select the clock source for Timer1. Table 17-2 displays the clock source selections.

17.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected, the TMR1H:TMR1L register pair will increment on multiples of FOSC as determined by the Timer1 prescaler.

When the FOSC internal clock source is selected, the Timer1 register value will increment by four counts every instruction clock cycle. Due to this condition, a 2 LSB error in resolution will occur when reading the Timer1 value. To utilize the full resolution of Timer1, an asynchronous input signal must be used to gate the Timer1 clock input.

The following asynchronous source may be used:

- Asynchronous event on the T1G pin to Timer1 gate

17.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When enabled to count, Timer1 is incremented on the rising edge of the external clock input T1CKI or the capacitive sensing oscillator signal. Either of these external clock sources can be synchronized to the microcontroller system clock or they can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1 enabled after POR
- Write to TMR1H or TMR1L
- Timer1 is disabled
- Timer1 is disabled (TMR1ON = 0) when T1CKI is high then Timer1 is enabled (TMR1ON = 1) when T1CKI is low.

TABLE 17-2: CLOCK SOURCE SELECTIONS

TMR1CS1	TMR1CS0	T1OSCEN	Clock Source
0	0	x	Instruction Clock (FOSC/4)
0	1	x	System Clock (FOSC)
1	0	0	External Clocking on T1CKI Pin
1	0	1	Osc. Circuit on T1OSI/T1OSO Pins
1	1	x	Reserved

FIGURE 17-5: TIMER1 GATE SINGLE-PULSE MODE

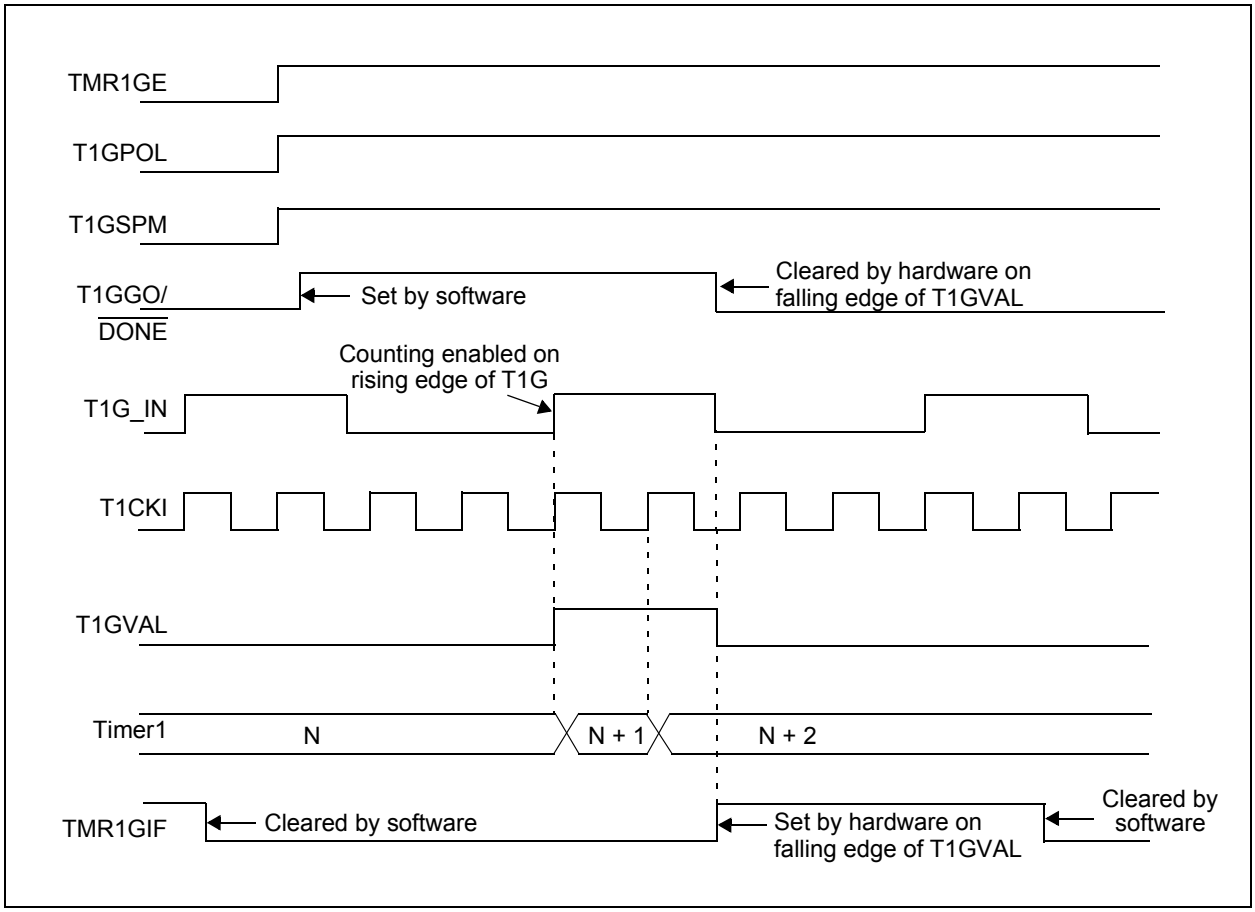
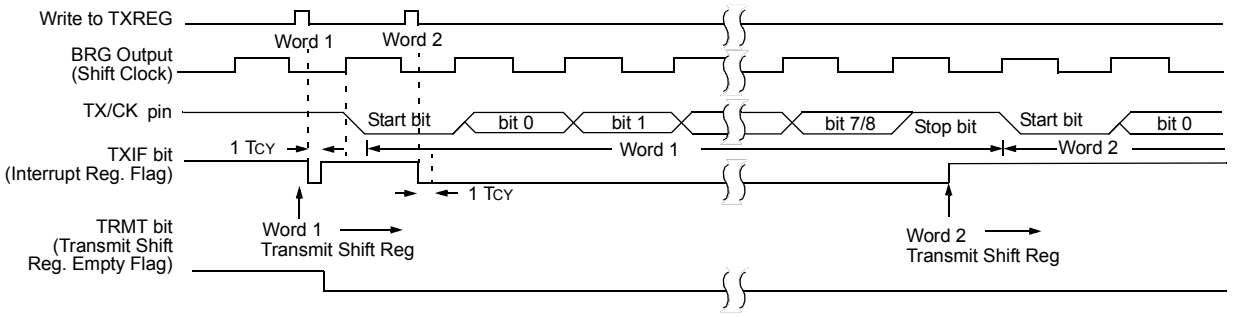


FIGURE 18-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 18-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TXREG	EUSART Transmit Register								144*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for asynchronous transmission.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

18.5.2 SYNCHRONOUS SLAVE MODE

The following bits are used to configure the EUSART for Synchronous slave operation:

- SYNC = 1
- CSRC = 0
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TXSTA register configures the device for synchronous operation. Clearing the CSRC bit of the TXSTA register configures the device as a slave. Clearing the SREN and CREN bits of the RCSTA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RCSTA register enables the EUSART. If the RX/DT or TX/CK pins are shared with an analog peripheral the analog I/O functions must be disabled by clearing the corresponding ANSEL bits.

RX/DT and TX/CK pin output drivers must be disabled by setting the corresponding TRIS bits.

18.5.2.1 EUSART Synchronous Slave Transmit

The operation of the Synchronous Master and Slave modes are identical (see **Section 18.5.1.3 "Synchronous Master Transmission")**, except in the case of the Sleep mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

1. The first character will immediately transfer to the TSR register and transmit.
2. The second word will remain in TXREG register.
3. The TXIF bit will not be set.
4. After the first character has been shifted out of TSR, the TXREG register will transfer the second character to the TSR and the TXIF bit will now be set.
5. If the PEIE and TXIE bits are set, the interrupt will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will call the Interrupt Service Routine.

18.5.2.2 Synchronous Slave Transmission Set-up:

1. Set the SYNC and SPEN bits and clear the CSRC bit.
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. Clear the CREN and SREN bits.
4. If using interrupts, ensure that the GIE and PEIE bits of the INTCON register are set and set the TXIE bit.
5. If 9-bit transmission is desired, set the TX9 bit.
6. Enable transmission by setting the TXEN bit.
7. If 9-bit transmission is selected, insert the Most Significant bit into the TX9D bit.
8. Start transmission by writing the Least Significant eight bits to the TXREG register.

REGISTER 19-1: LCDCON: LIQUID CRYSTAL DISPLAY (LCD) CONTROL REGISTER

R/W-0/0	R/W-0/0	R/C-0/0	U-0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1
LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **LCDEN:** LCD Driver Enable bit
1 = LCD driver module is enabled
0 = LCD driver module is disabled

bit 6 **SLPEN:** LCD Driver Enable in Sleep Mode bit
1 = LCD driver module is disabled in Sleep mode
0 = LCD driver module is enabled in Sleep mode

bit 5 **WERR:** LCD Write Failed Error bit
1 = LCDDATAn register written while the WA bit of the LCDPS register = 0 (must be cleared in software)
0 = No LCD write error

bit 4 **Unimplemented:** Read as '0'

bit 3-2 **CS<1:0>:** Clock Source Select bits
00 = FOSC/256
01 = T1OSC (Timer1)
1x = LFINTOSC (31 kHz)

bit 1-0 **LMUX<1:0>:** Commons Select bits

LMUX<1:0>	Multiplex	Maximum Number of Pixels		Bias
		PIC16LF1906	PIC16LF1904/7	
00	Static (COM0)	19	29	Static
01	1/2 (COM<1:0>)	38	58	1/2 or 1/3
10	1/3 (COM<2:0>)	57	87	1/2 or 1/3
11	1/4 (COM<3:0>)	72(1)	116	1/3

Note 1: On these devices, COM3 and SEG15 are shared on one pin, limiting the device from driving 72 segments.

19.4.3 AUTOMATIC POWER MODE SWITCHING

As an LCD segment is electrically only a capacitor, current is drawn only during the interval where the voltage is switching. To minimize total device current, the LCD internal reference ladder can be operated in a different power mode for the transition portion of the duration. This is controlled by the LCDRL Register (Register 19-7).

The LCDRL register allows switching between two power modes, designated ‘A’ and ‘B’. ‘A’ Power mode is active for a programmable time, beginning at the time when the LCD segments transition. ‘B’ Power mode is the remaining time before the segments or commons change again. The LRLAT<2:0> bits select how long, if any, that the ‘A’ Power mode is active. Refer to Figure 19-4.

To implement this, the 5-bit prescaler used to divide the 32 kHz clock down to the LCD controller’s 1 kHz base rate is used to select the power mode.

FIGURE 19-4: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE A

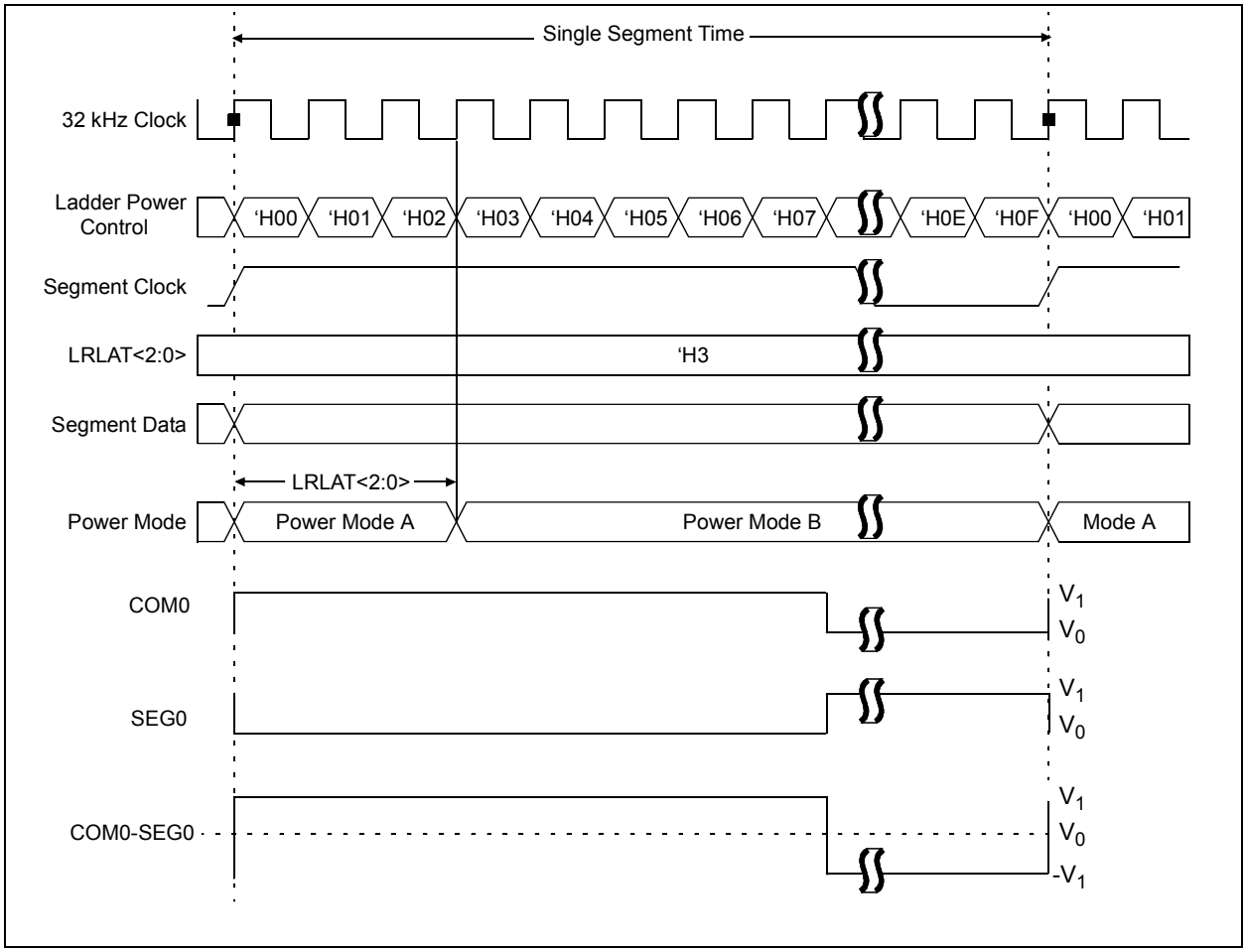
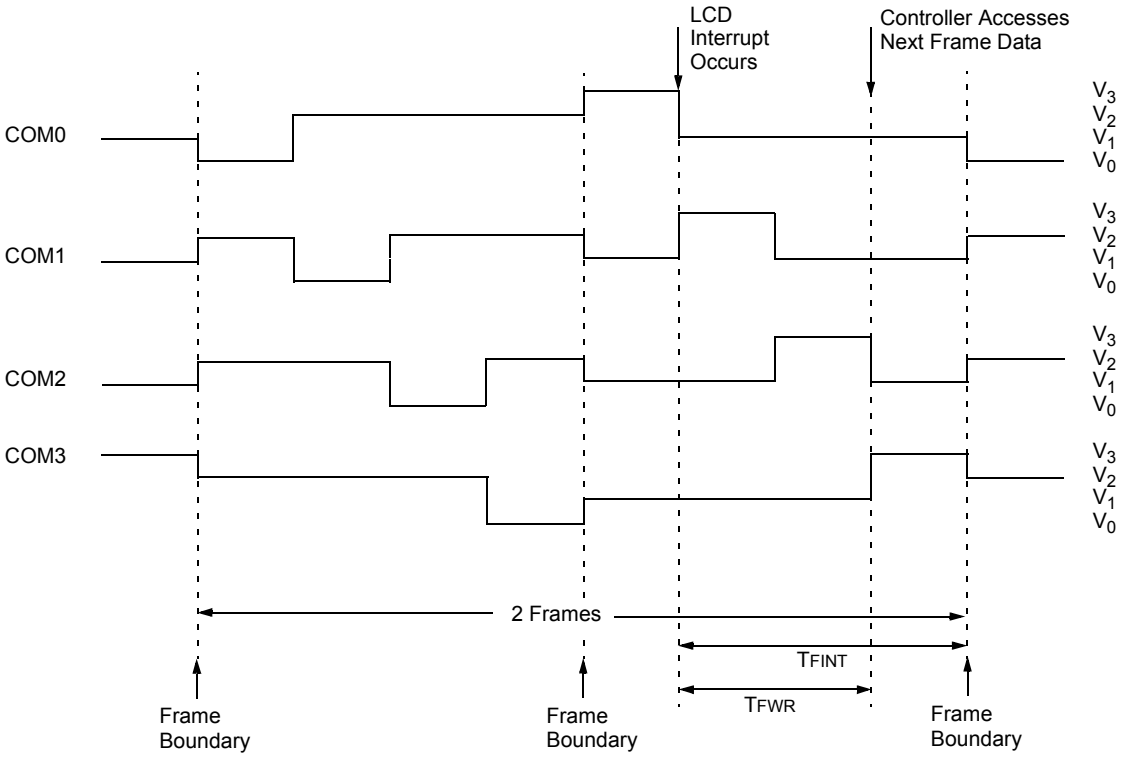


FIGURE 19-19: WAVEFORMS AND INTERRUPT TIMING IN QUARTER-DUTY CYCLE DRIVE (EXAMPLE – TYPE-B, NON-STATIC)



$T_{FWR} = T_{FRAME}/2*(LMUX<1:0> + 1) + T_{CY}/2$

$T_{FINT} = (T_{FWR}/2 – (2\ T_{CY} + 40\ ns)) \rightarrow \text{minimum} = 1.5(T_{FRAME}/4) – (2\ T_{CY} + 40\ ns)$
$(T_{FWR}/2 – (1\ T_{CY} + 40\ ns)) \rightarrow \text{maximum} = 1.5(T_{FRAME}/4) – (1\ T_{CY} + 40\ ns)$

TABLE 22-5: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
		Program Memory Programming Specifications					
D110	VIHH	Voltage on $\overline{MCLR}$/VPP/RE3 pin	8.0	—	9.0	V	**(Note 2)**
D111	IDDP	Supply Current during Programming	—	—	10	mA	
D112		VDD for Bulk Erase	2.7	—	VDD max.	V	
D113	VPEW	VDD for Write or Row Erase	VDD min.	—	VDD max.	V	
D114	IPPPGM	Current on $\overline{MCLR}$/VPP during Erase/Write	—	—	1.0	mA	
D115	IDDPGM	Current on VDD during Erase/Write	—		5.0	mA	
		Program Flash Memory					
D121	EP	Cell Endurance	1K	10K	—	E/W	-40°C to +85°C (**Note 1**)
D122	VPR	VDD for Read	VDD min.	—	VDD max.	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

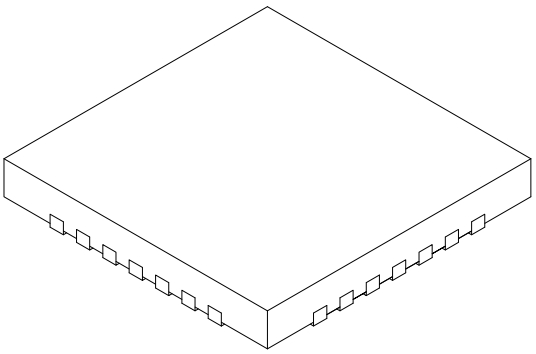
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Required only if single-supply programming is disabled.

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.55	2.65	2.75
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.55	2.65	2.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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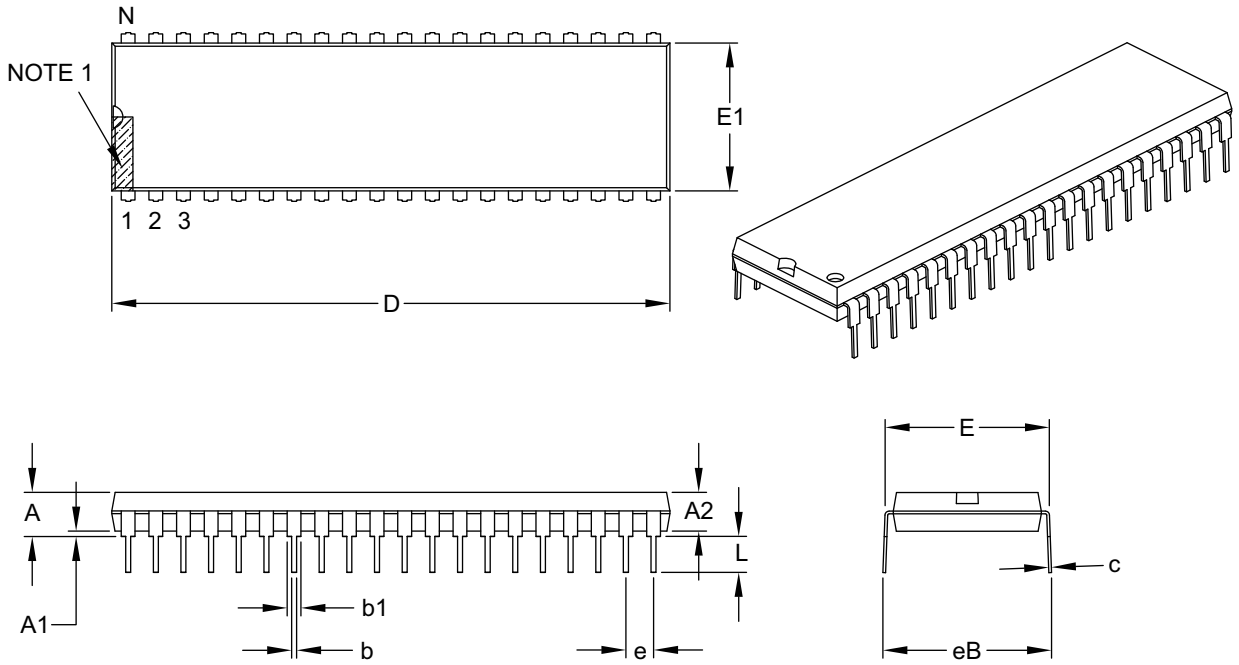
40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B